preliminary

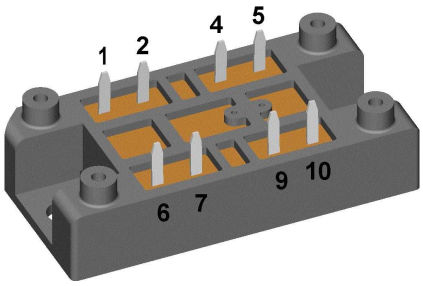
XPT IGBT Module

V_{CES} = 1200 V
I_{C25} = 250 A
$V_{CE(sat)}$ = 1.7 V

Boost Chopper

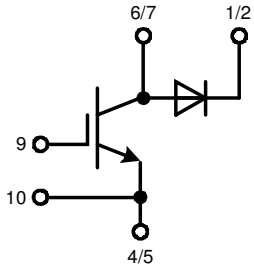
Part number

MIXA150R1200VA



Backside: isolated

E72873



Features / Advantages:

- Easy paralleling due to the positive temperature coefficient of the on-state voltage
- Rugged XPT design (Xtreme light Punch Through) results in:
  - short circuit rated for 10 µsec.
  - very low gate charge
  - low EMI
  - square RBSOA @ 3x Ic
- Thin wafer technology combined with the XPT design results in a competitive low VCE(sat)
- SONIC™ diode
  - fast and soft reverse recovery
  - low operating forward voltage

Applications:

- AC motor drives
- Solar inverter
- Medical equipment
- Uninterruptible power supply
- Air-conditioning systems
- Welding equipment
- Switched-mode and resonant-mode power supplies
- Inductive heating, cookers
- Pumps, Fans

Package: V1-A-Pack

- Isolation Voltage: 3600 V~
- Industry standard outline
- RoHS compliant
- Soldering pins for PCB mounting
- Height: 17 mm
- Base plate: DCB ceramic
- Reduced weight
- Advanced power cycling

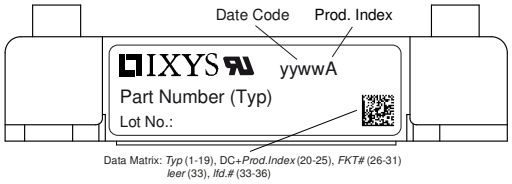
preliminary

IGBT				Ratings			
Symbol	**Definition**	**Conditions**		**min.**	**typ.**	**max.**	**Unit**
V_{CES}	*collector emitter voltage*		T_{VJ} = 25°C			1200	V
V_{GES}	*max. DC gate voltage*					±20	V
V_{GEM}	*max. transient gate emitter voltage*					±30	V
I_{C25}	*collector current*		T_C = 25°C			250	A
I_{C80}			T_C = 80°C			175	A
P_{tot}	*total power dissipation*		T_C = 25°C			695	W
$V_{CE(sat)}$	*collector emitter saturation voltage*	I_C = 150 A; V_{GE} = 15 V	T_{VJ} = 25°C		1.7	2.1	V
			T_{VJ} = 125°C		1.9		V
$V_{GE(th)}$	*gate emitter threshold voltage*	I_C = 6 mA; V_{GE} = V_{CE}	T_{VJ} = 25°C	6	6.8	7.5	V
I_{CES}	*collector emitter leakage current*	V_{CE} = V_{CES}; V_{GE} = 0 V	T_{VJ} = 25°C			0.1	mA
			T_{VJ} = 125°C		0.1		mA
I_{GES}	*gate emitter leakage current*	V_{GE} = ±20 V				500	nA
$Q_{G(on)}$	*total gate charge*	V_{CE} = 600 V; V_{GE} = 15 V; I_C = 150 A			510		nC
$t_{d(on)}$	*turn-on delay time*				220		ns
t_r	*current rise time*				100		ns
$t_{d(off)}$	*turn-off delay time*	inductive load	T_{VJ} = 125°C		400		ns
t_f	*current fall time*	V_{CE} = 600 V; I_C = 150 A			220		ns
E_{on}	*turn-on energy per pulse*	V_{GE} = ±15 V; R_G = 1.2 Ω			21.5		mJ
E_{off}	*turn-off energy per pulse*				17		mJ
RBSOA	*reverse bias safe operating area*	V_{GE} = ±15 V; R_G = 1.2 Ω	T_{VJ} = 125°C				
I_{CM}		V_{CEmax} = 1200 V				450	A
SCSOA	*short circuit safe operating area*	V_{CEmax} = 1200 V					
t_{SC}	*short circuit duration*	V_{CE} = 900 V; V_{GE} = ±15 V	T_{VJ} = 125°C			10	µs
I_{SC}	*short circuit current*	R_G = 1.2 Ω; non-repetitive			650		A
R_{thJC}	*thermal resistance junction to case*					0.16	K/W
R_{thCH}	*thermal resistance case to heatsink*				0.10		K/W

Diode							
V_{RRM}	*max. repetitive reverse voltage*		T_{VJ} = 25°C			1200	V
I_{F25}	*forward current*		T_C = 25°C			190	A
I_{F80}			T_C = 80°C			130	A
V_F	*forward voltage*	I_F = 150 A	T_{VJ} = 25°C			2.20	V
			T_{VJ} = 125°C		1.95		V
I_R	*reverse current*	V_R = V_{RRM}	T_{VJ} = 25°C			0.3	mA
			T_{VJ} = 125°C		0.8		mA
Q_{rr}	*reverse recovery charge*				20		µC
I_{RM}	*max. reverse recovery current*	V_R = 600 V			175		A
t_{rr}	*reverse recovery time*	-di_F/dt = 2500 A/µs	T_{VJ} = 125°C		350		ns
E_{rec}	*reverse recovery energy*	I_F = 150 A; V_{GE} = 0 V			10		mJ
R_{thJC}	*thermal resistance junction to case*					0.28	K/W
R_{thCH}	*thermal resistance case to heatsink*				0.20		K/W

preliminary

Package V1-A-Pack				Ratings			
Symbol	**Definition**	**Conditions**		**min.**	**typ.**	**max.**	**Unit**
I_{RMS}	*RMS current*	per terminal				100	A
T_{VJ}	*virtual junction temperature*			-40		150	°C
T_{op}	*operation temperature*			-40		125	°C
T_{stg}	*storage temperature*			-40		125	°C
Weight					37		g
M_D	*mounting torque*			2		2.5	Nm
$d_{Spp/App}$	*creepage distance on surface | striking distance through air*		*terminal to terminal*	6.0			mm
$d_{Spb/Apb}$			*terminal to backside*	12.0			mm
V_{ISOL}	*isolation voltage*	t = 1 second	50/60 Hz, RMS; I_{ISOL} ≤ 1 mA	3600			V
		t = 1 minute		3000			V

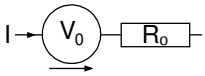


Part description

M = Module
I = IGBT
X = XPT IGBT
A = Gen 1 / std
150 = Current Rating [A]
R = Boost Chopper
1200 = Reverse Voltage [V]
VA = V1-A-Pack

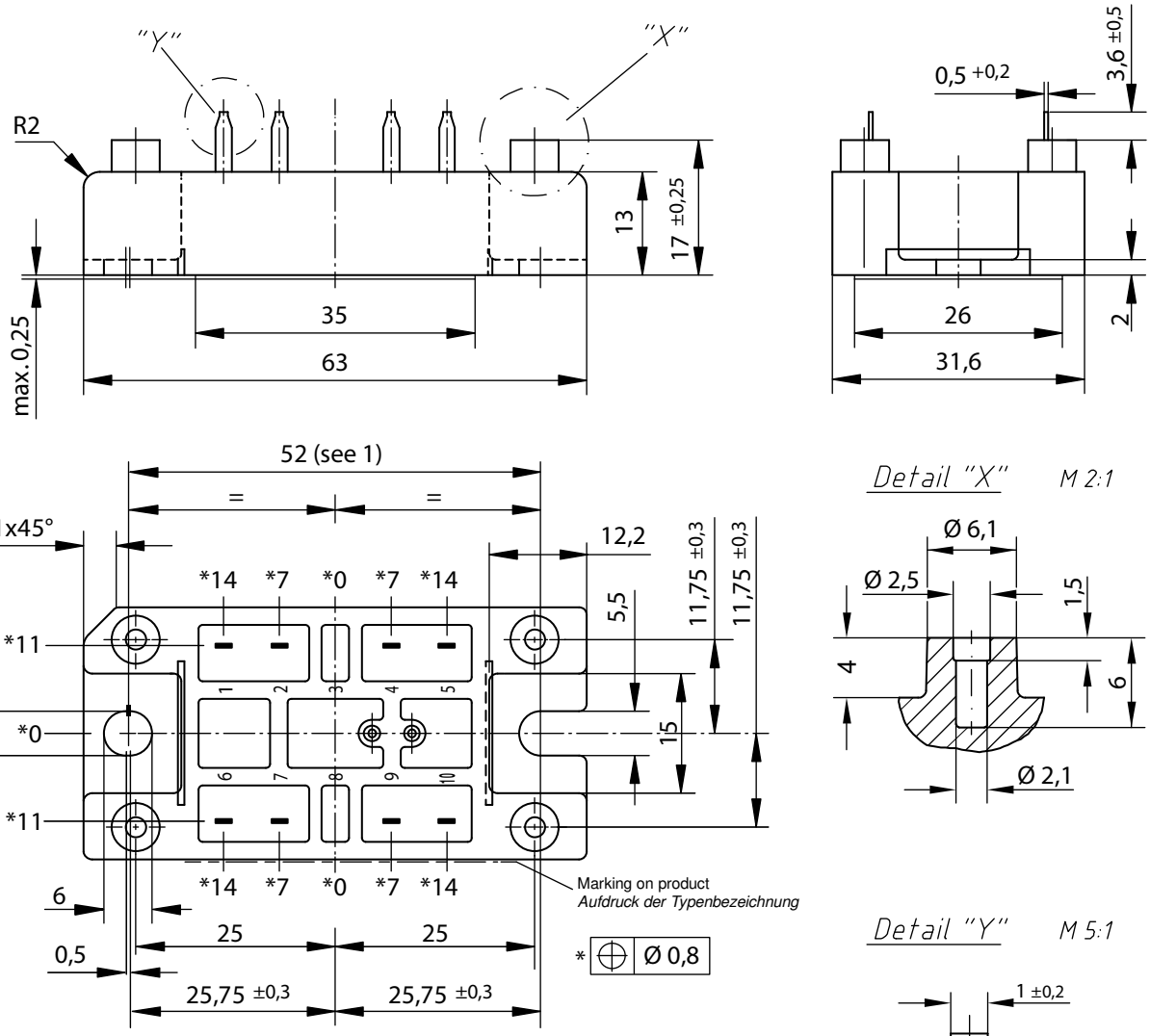
Ordering	Ordering Number	Marking on Product	Delivery Mode	Quantity	Code No.
Standard	MIXA150R1200VA	MIXA150R1200VA	Blister	24	511595

Equivalent Circuits for Simulation ** on die level* T_{VJ} = 150 °C



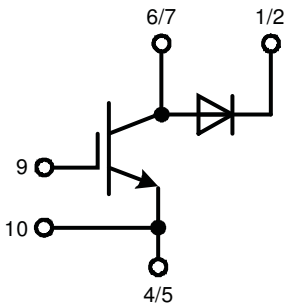
		IGBT	Diode	
$V_{0\,max}$	*threshold voltage*	1.1	1.25	V
$R_{0\,max}$	*slope resistance **	9.2	5.7	mΩ

Outlines V1-A-Pack



Remarks / ***Bemerkungen:***

1. Nominal distance mounting screws on heat sink: 52 mm / *Nennabstand Befestigungsschrauben auf Kühlkörper: 52 mm*
2. General tolerance / *Allgemeintoleranz*: DIN ISO 2768 -T1-c
3. Surface treatment of pins: tin plated (Sn) in hot dip / *Oberflächenbehandlung der Pins: verzinnt (Sn) im Tauchbad*
4. *Detail X*:
   EJOT PT® self-tapping screws (dimension K25) to be recommended for mounting on PCB
   selbstschneidende Schraube (Größe K25) empfohlen für die PCB-Montage
   Take care on the maximum screw length according to board thickness and the maximum hole depth of 6 mm
   Bei der Wahl der Schraubenlänge die PCB-Dicke und die maximale Lochtiefe von 6mm beachten
   Recommended mounting torque: 1.5 Nm / *Empfohlenes Drehmoment: 1.5 Nm*



IGBT

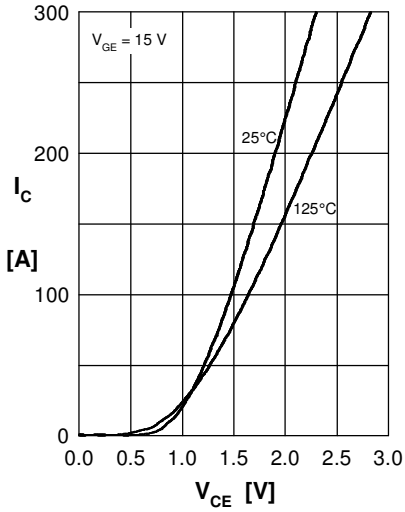


Fig.1 Output characteristics IGBT

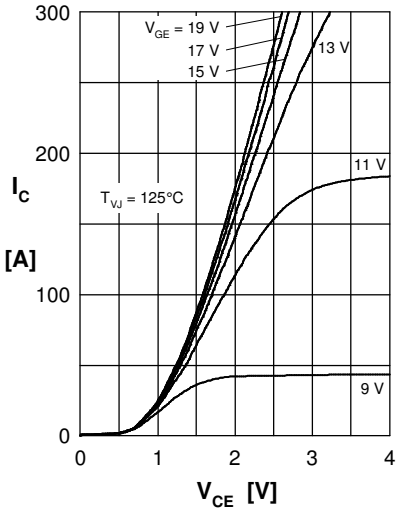


Fig.2 Typ. output characteristics IGBT

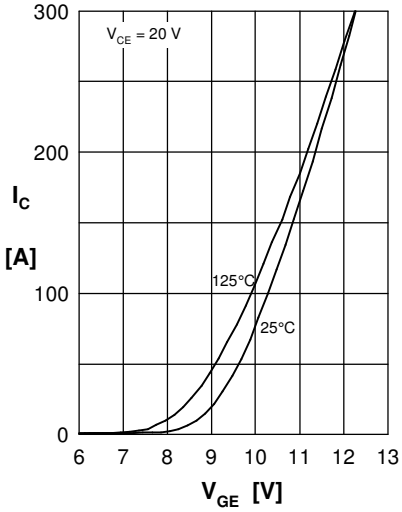


Fig. 3 Typ. transfer charact. IGBT

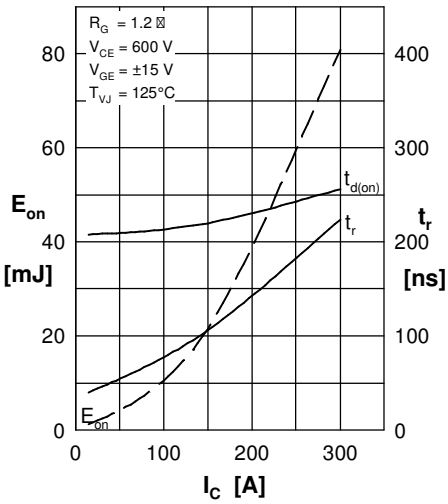


Fig. 4 Typ. turn-on energy & switch. times vs. collector current

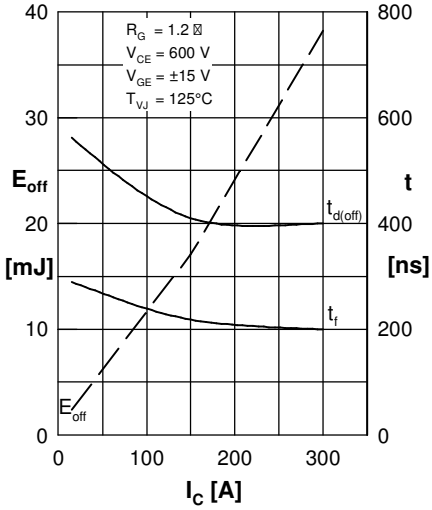


Fig. 5 Typ. turn-off energy & switch. times vs. collector current

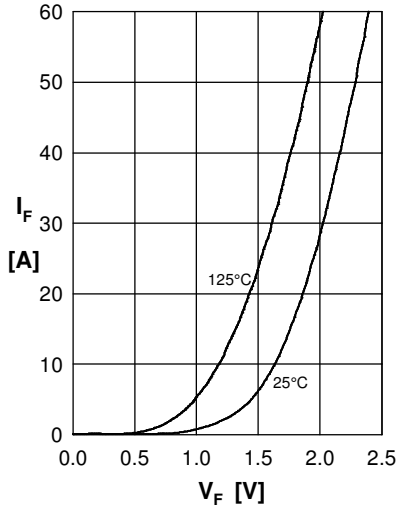


Fig. 6 Typ. forward characteristics Diode

Fig. 7 Typ. reverse recovery characteristics Diode

Fig. 8 Typ. reverse recovery characteristics Diode

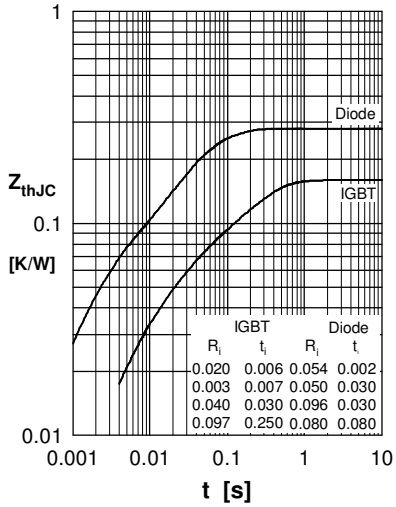


Fig. 9 Transient thermal resistance junction to case